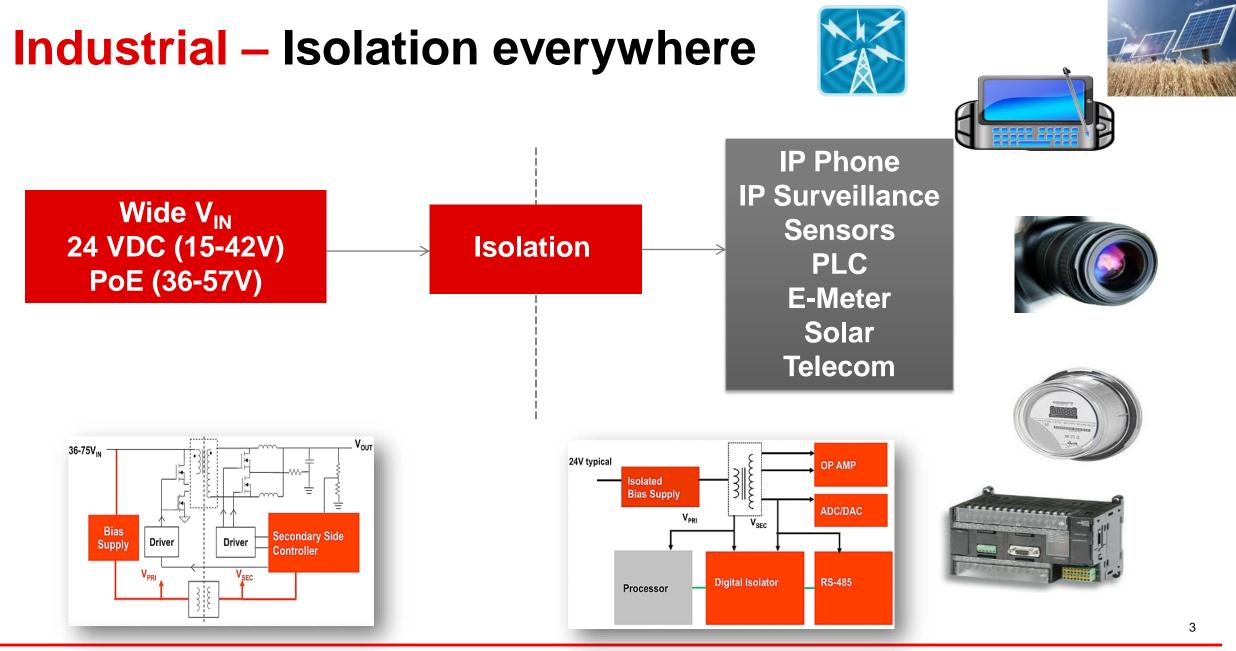
Simple, high-performance, isolated power supply design with PSR (no-opto) flyback

Marshall Beck July 2021



Agenda

- Isolation in industrial applications
- PSR flyback:
 - PSR vs conventional flyback, control/operation, and TI offerings
- PSR flyback simple design flow
- TI supporting content on PSR flyback design

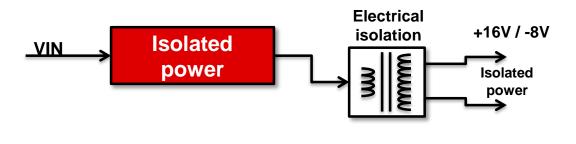


TI Information – Selective Disclosure

🤴 Texas Instruments

Where to use isolation?

- Safety
 - Mandatory by safety standards to isolate the user from the hazardous voltage of a power supply. Protect user from ESD and surge events.
 - Typical applications: IP camera, solar inverter, factory automation field site
- Break ground loop, mitigate noise
 - Installed to break the ground loop interference for noise-sensitive applications
 - Typical applications : PLCs, solar inverters, building automation (ie. RS232/485, etc.)
- Inversion, level shifting & multiple rails
 - Isolated output voltage can be conveniently configured as multiple isolated outputs, as a negative voltage rail or as a level-shifted voltage rail.
 - Typical applications : test and measurement, medical, e-bike, HVAC, motor drives

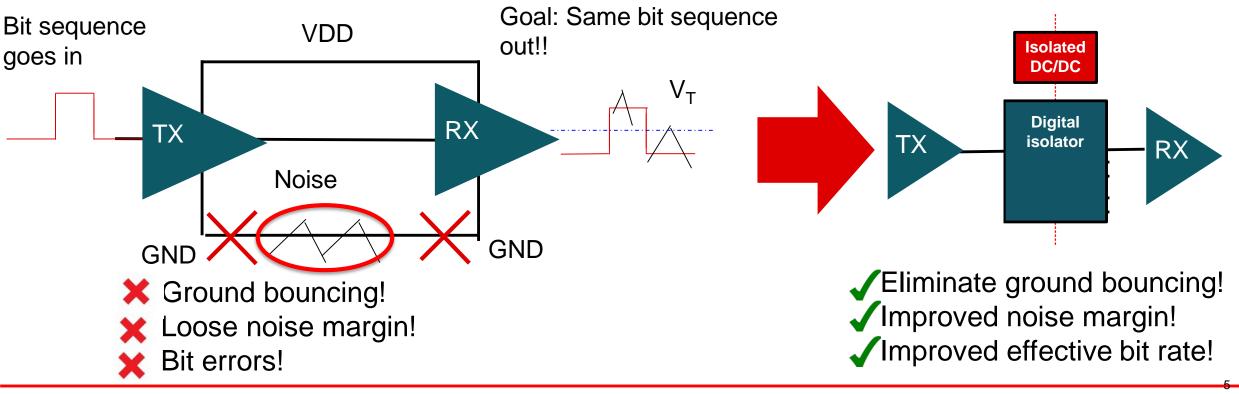




Isolation

Isolated power – Simplify signal integrity!

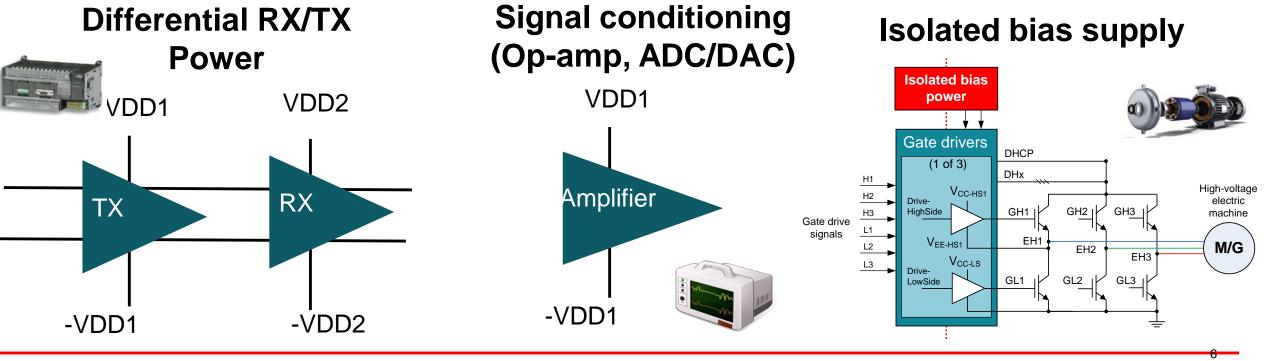
- Typical communication protocols: RS422/485, RS232, RS285, LVDS, Ethernet
- Long cabling causes transient voltage differences and possible errors!
- Solution: Isolate the TX and RX power!



TEXAS INSTRUMENTS

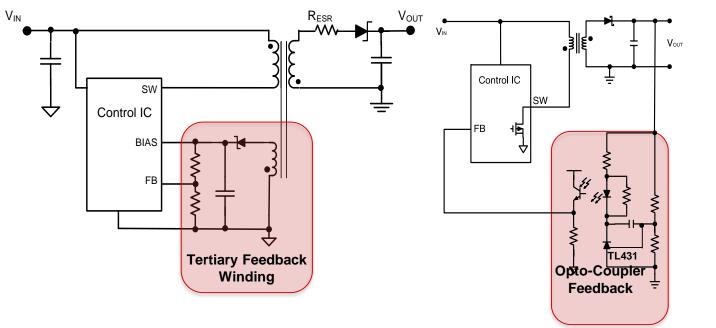
Isolated power – Simplify your power tree!

- Isolated output voltages can be conveniently configured as multiple isolated outputs, as a negative voltage rail or as a level-shifted voltage rail.
- **Example use cases**: Positive/negative rails for differential digital communications, op-amp, isolated bias supply for gate driver



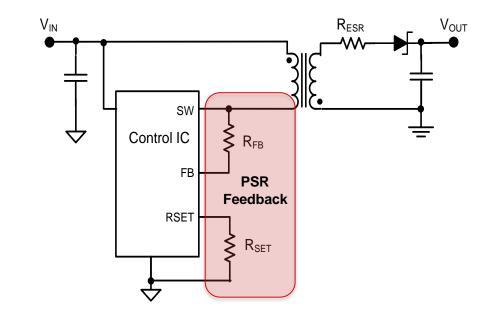
Texas Instruments

Conventional PSR flyback vs. Aux-less PSR flyback



Conventional PSR flyback advantages:

- Increased design flexibility with external compensation and tertiary winding or optocoupler feedback
- Operates in CCM (fixed frequency) or DCM mode

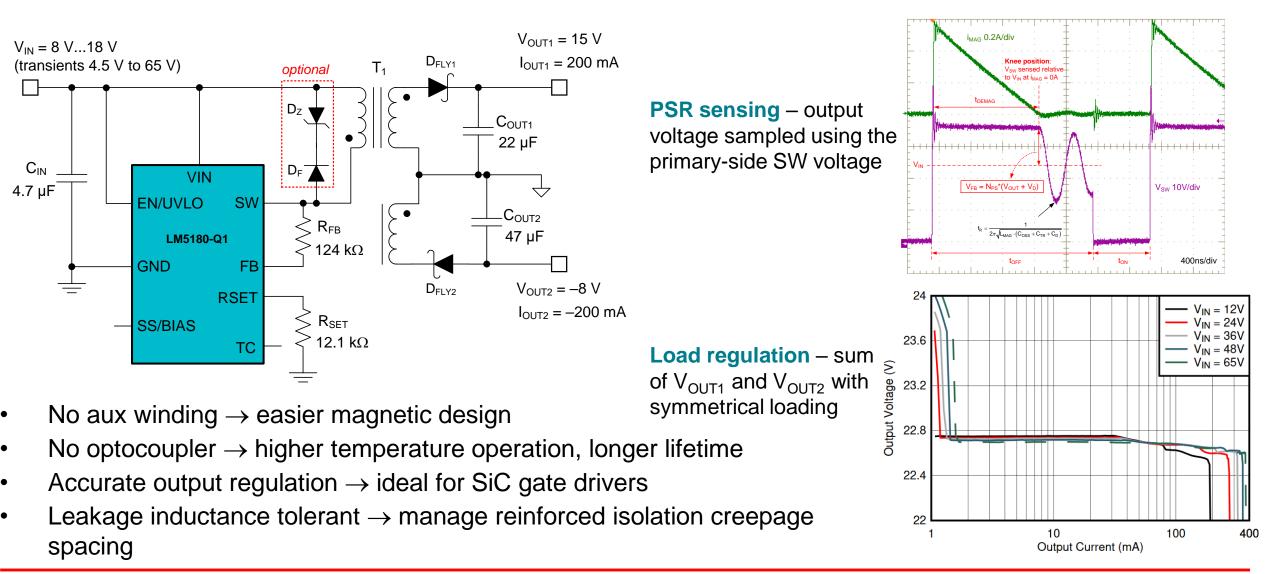


Aux-less PSR flyback advantages:

- Eliminates opto-coupler or tertiary winding with only one component crossing isolation barrier
- Extremely tight load regulation (±1%)
- Operates in DCM or Boundary Mode
- DCM and zero current switching enables high efficiency
 7



PSR flyback converter – no opto, no aux winding



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PSR flyback DC/DC family overview

PSR Flyback DC/DC Converter	Input Voltage Range	Peak Switch Current	Maximum Load Current V _{OUT} = 12 V, N _{PS} = 1, V _{IN} = 13.5V	Package Option
<u>LM5181</u>	4.5 V to 65 V	0.75 A	180 mA	WSON-8
<u>LM5180</u>	4.5 V to 65 V	1.5 A	360 mA	WSON-8
<u>LM25180</u>	4.5 V to 42 V	1.5 A	360 mA	WSON-8
<u>LM25183</u>	4.5 V to 42 V	2.5 A	600 mA	WSON-8
<u>LM25184</u>	4.5 V to 42 V	4.1 A	1 A	WSON-8



LM25183-Q1/LM25184-Q1

Highest power density 42V, 2.5A/4A primary side regulated (PSR) flyback converter with 65V integrated power MOSFET

Features

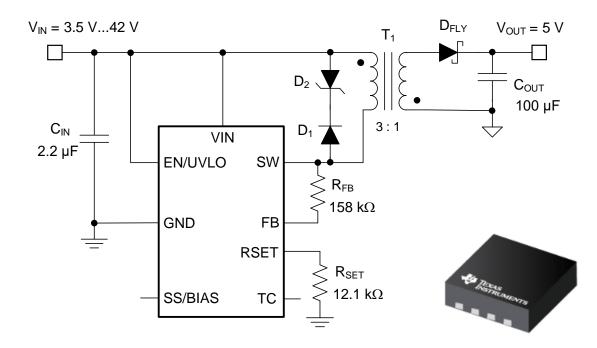
- Highest Power Density 42V PSR with tightest Output Regulation in its class
- 65V, 2.5A/4A internal power MOSFET
- **4.5V–42V wide V_{IN} range** (abs max 45V)
 - $\circ~$ 3.5V minimum V_{IN} after start-up
- V_{OUT} accuracy ±1% achievable
 - $V_{IN} = 6V-42V$, $V_{OUT} = 5V$, 2% load to full load
 - $T_A = -40^{\circ}C$ to 125°C
- Boundary mode, quasi-resonant operation
- Internal loop compensation, adjustable input UVLO
- External V_{CC} bias option for improved efficiency
- Adjustable or fixed internal 6ms soft-start
- Optional V_{OUT} temperature compensation
- 4 mm × 4 mm WSON-8 WF package, 0.8mm pitch
- AEC-Q100 grade 1 \Rightarrow 125°C operating ambient range

Applications

- Factory automation, PLC
- Motor drive, telcom, solar, IP

Benefits

- > No opto-coupler or transformer auxiliary winding needed
- > Accurate V_{OUT} regulation performance with sensing at zero current
- Low I_Q operation and external BIAS rail option enable high efficiency at light loads

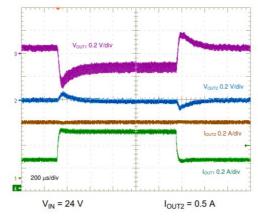






LM25184 performance curves

Low-heat generation



Modest F_{SW} enables good transient performance and small magnetics

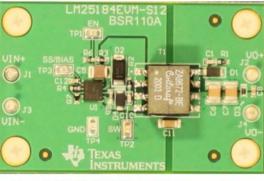
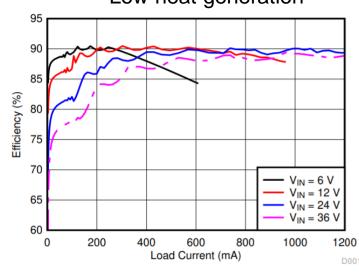
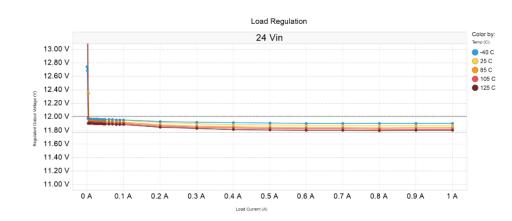


Figure 2. LM25184 EVM (Top Side), 56 mm × 36 mm



Typical Efficiency, V_{OUT} = 12 V



<1.7% variance from -40degC to 125degC

Figure 8-25. Positive Output Load Transient, 0.25 A to 0.5 A

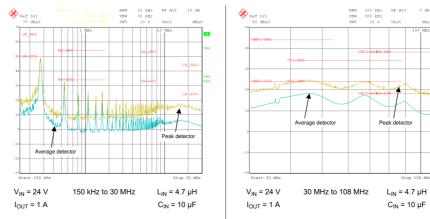


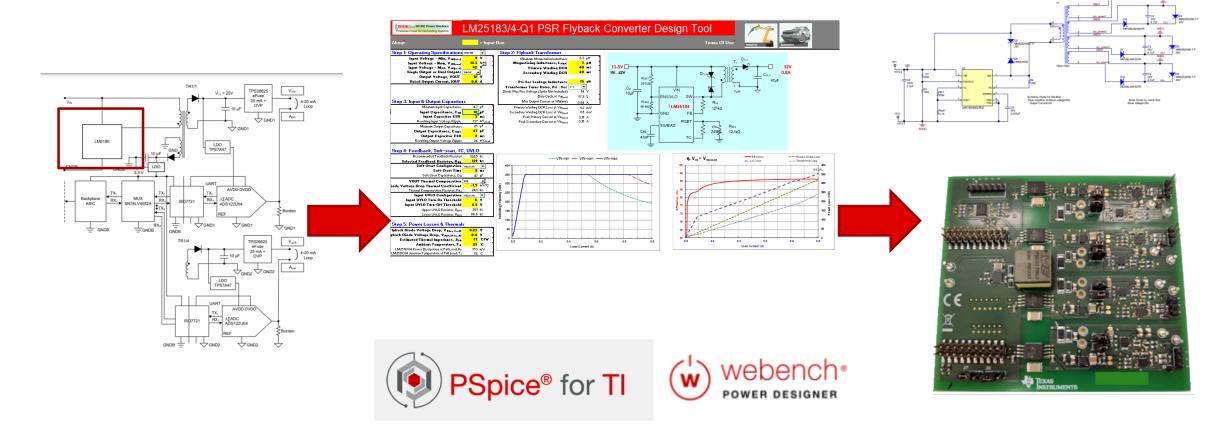
Figure 8-14. CISPR 25 Class 5 Conducted EMI Plot Figure 8-15. CISPR 25 Class 5 Conducted EMI Plot

Passes stringent EMC standards with only differential filtering



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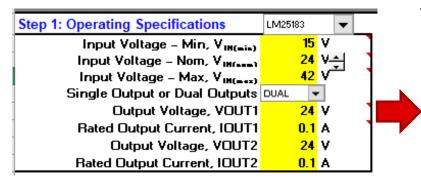
TI's simple design flow



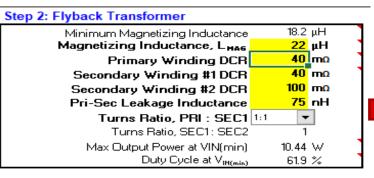


Design calculator tool

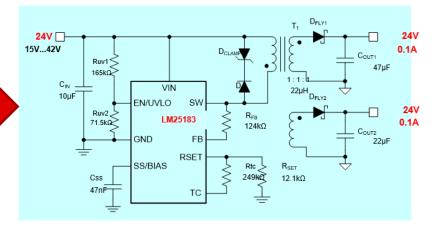
Input power conditions



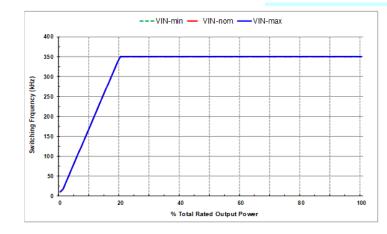
Input xfm spec

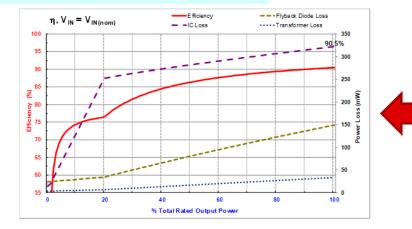


Get SCH and BOM



Evaluate performance





Ref Des	Value	Description	Size	•	Part Number	MFR	Footprint (mm)	Area (mm ²)
CIN	10µF	Capacitor, Ceramic, 10µF, 100V, X7R, 10%	1210	-	Std	Std	3.2 x 2.5	8.0
Cour	47µF	Capacitor, Ceramic, 47µF, 50V, X7R, 10%	1210	-	Std	Std	3.2 x 2.5	8.0
C _{OUT2}	22µF	Capacitor, Ceramic, 22µF, 50V, X7R, 10%	1210	-	Std	Std	3.2 x 2.5	8.0
Css	47nF	Capacitor, Ceramic, 47nF, 16V, X7R, 10%	0402	-	Std	Std	1.0 x 0.5	0.5
DFLY	Diode	Rectifying Diode, Schottky	SMA	-	Std	Std	5.0 x 2.5	12.5
D _{FLY2}	Diode	Rectifying Diode, Schottky	SOD123	•	Std	Std	3.6 x 1.8	6.5
DF	Diode	Clamp Circuit Diode, Fast Recovery	SOD123	-	Std	Std	3.6 x 1.8	6.5
DCLAMP	24V	Clamp Circuit Diode, Zener, 24V	SOD123	-	Std	Std	3.6 x 1.8	6.5
Dout	26.4V	Output Clamp Diode, Zener, 27V	SOD523	•	Std	Std	1.6 x 0.8	1.3
R _{SET}	12.1k	Resistor, Chip, 12.1kΩ, 1/16W, 1%	0402	-	Std	Std	1.0 x 0.5	0.5
R _{FB}	124k	Resistor, Chip, 124kΩ, 1/16W, 1%	0402	-	Std	Std	1.0 x 0.5	0.5
R _{UV1}	165k	Resistor, Chip, 165kΩ, 1/16W, 1%	0402	-	Std	Std	1.0 x 0.5	0.5
R _{UV2}	71.5k	Resistor, Chip, 71.5kΩ, 1/16W, 1%	0402	-	Std	Std	1.0 x 0.5	0.5
RTC	249k	Resistor, Chip, 249kQ, 1/16W, 1%	0402	-	Std	Std	1.0 x 0.5	0.5
T ₁	22µH	Transformer, 22μH, 1 : 1 : 1, 40mΩ Pri DCR, 3A Isat	10mm × 10mm	-	Various	Various	10 x 10	100
U1	LM25183	IC, LM25183, PSR Flyback Converter, 4.5V-42V Input	WSON-8		LM25183NGUR	п	4.0 x 4.0	16.0

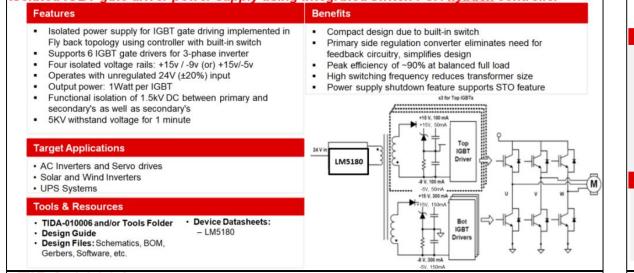
Total Solution Size (buffered by 25%) 220.4 mm² =



Released reference designs

TIDA-010006

Isolated IGBT gate driver power supply using integrated switch PSR flyback controller



TIDA-020014

HEV/EV traction inverter power stage reference design with 3 types of IGBT/SiC bias supply solutions

Design Features

- 4.5V to 45V input, +15V and -9V outputs, configurable into +20V, -4V outputs
- · Directly driven by 12V car battery with increased safety level Wide-Vin during very low dips in input voltage of 4.5V and up to 45V DC
- No Opto coupler
- · Low IQ operation at no-load current
- High efficiency at light loads

Tools & Resources

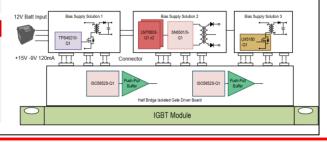
- Expected complexity of the TI Design
 - # of IC's: 5 (LM5180-Q1, TPS40210-Q1, LM76003-Q1*2, SN6501-Q1/SN6505-Q1, LM74700-Q1*3)
 - # of passives: ~140 into 3 boards
 - PCB dimensions: ~40mm*40mm each board
 - # of PCB lavers: 2
 - · Firmware needs: N/A

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Design Benefits

- · A comprehensive design with multiple bias supply solutions for IGBT/SiC isolated gate drivers in HEV/EV
- · Multiple solutions including PSR Flyback Converter, Flyback Controller, Buck + Push-pull
- Small size, compact, cost effective
- · Plug in connection to IGBT driver board for easy HV evaluation
- Compatible Isolated Gate Driver board included for customer evaluation



TIDA-020015

4.5V to 70V input bias supply with power stage reference design for Automotive **IGBT/SiC** gate drivers

Design Features

- Directly driven by 12V car battery which eliminates risk from intermediate power rail failure
- VOUT accuracy ±1% achievable
- VIN = 4.5V-70V, VOUT = +15V & -9V, ~180mA, 5% regulation to full load
- TA = -40°C to 125°C
- · Boundary mode, guasi-resonant operation
- Internal loop compensation · no need to extra clamping circuit, fits both 12V battery & 48V battery inputs
- Tested for ISO 7637-2:2004 conducted transient immunity compliance. including Load Dump

Tools & Resources

· Expected complexity of the TI Design

- # of IC's: 2 (LM5180-Q1+LM74700-Q1)
- # of passives: ~35
- PCB dimensions: ~40mm*40mm
- # of PCB lavers: 2
- Firmware needs: N/A

TI Information - Selective Disclose TIDACBL-0039 Intrinsic Safe Analog Input Module

Features

- 1 to 4 channel-channel isolated Intrinsic Safe AI
- · Supply for the Field Transmitters with output power
- limitation (short limited to 35mA().
- Input protected against miswiring (wiring to 24V)
- Transmitter supply: 26 +/-1V, lout <35mA peak
- · Input: short to L+ and GND protected, 24b accuracy

Applications

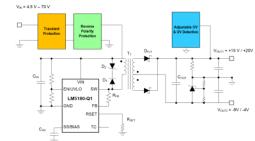
- · Robotics Analog Input Module for IS application
- PLC Analog Input Module

Additional details

:	Key devices: LM5180, TPS2662, ADS122U04 Why is this design considered: • how to protect output power for	IS AI and how to protect inputs from shorts Public market info : IS application fast growing in Factory Automation Technical status : Design phase
	TI Information – Selective Disclosure	

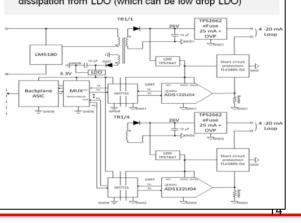
Design Benefits

- · Easy-to-use, highly integrated, PSR flyback solution as Bias Power
- · No opto-coupler or transformer auxiliary winding needed
- · Low IQ operation at no-load current
- High efficiency at light loads
- Accurate V_{OLT} regulation performance with sensing at zero current
- Low In operation and external BIAS rail option enable high efficiency at light loads

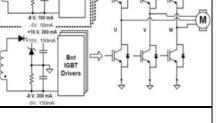




- · Short circuit protection on power output
- · Mis-wiring protections on the Analog Input · High-accuracy LM5180 allows to minimise heat dissipation from LDO (which can be low drop LDO)







PSR flyback references

LM25184 Single-Output EVM User's Guide

LM5180 Single-Output EVM User's Guide

LM5180 Dual-Output EVM User's Guide

How an Auxless PSR Flyback Converter can Increase PLC Reliability and Density

Why Use PSR-Flyback Isolated Converters in Dual-Battery mHEV Systems

PSR Flyback DC/DC Converter Transformer Design for mHEV Applications

Flyback Transformer Design Considerations for Efficiency and EMI

Under the Hood of Flyback SMPS Designs



Conclusion

- Isolated power sockets exist everywhere!
 - Medical and test & measurement, sensors in factory and building automation: split rails for signal conditioning circuit (ie. op-amp, DAC/ADC)
 - Factory automation, building automation, communications, and solar: isolated power needed to ensure high signal integrity, with more and more sensors & faster speeds, signal integrity concerns only increase!
 - Inverters in HVAC Systems, E-bike, Motor Drives: Isolated gate driver requires isolated gate bias. SiC requires tighter regulation which is a great fit for No-opto PSR flyback.





Thank you!

PSR flyback converter – magnetic design considerations



Engaging with the magnetic component vendor

Key Specification	Symbol		Purpose
Turns ratio	N _{PS}		Optimize flyback duty cycle range
Switching frequency	F _{SW}		Control core loss
Magnetizing inductance	L _{MAG}	-	Set PSR flyback mode boundaries
Saturation current (at 20°C)	I _{SAT}		Prevent magnetic saturation
Primary and secondary DCRs (at 20°C)	R_{PRI}, R_{SEC}		Reduce copper loss
Winding arrangement – interleaving, # of layers			Minimize R_{AC} and L_{LEAK}
Leakage inductance	L _{LEAK}		Reduce power loss & voltage spikes
Interwinding capacitance	C _{P-S}		Mitigate common-mode EMI
Hi-pot test limits (dielectric withstand)	V _{ISO(PRI-SEC)}		Provide a robust design
Insulation rating – functional / basic / reinforced	IR		Comply with safety requirements
Operating temperature range	$T_{AMB} + T_{RISE}$		Ensure reliability
Mechanicals – pinout, footprint, height	$L\timesW\timesH$		Minimize size and cost

Flyback transformer losses

Copper loss

- DC resistance depends on the wire cross-section and length (N, MLT)
- $_{\odot}$ AC resistance depends on choice of wire diameter vs. F_{SW} and construction (layer stackup, proximity effects, gap effect)

Core loss

Ο

 $_{\odot}$ Related to core material characteristics, $B_{DC},\,B_{AC},\,F_{SW}$

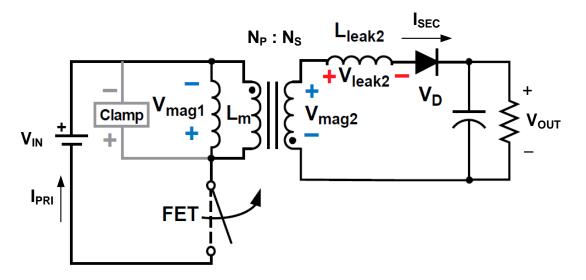
• External loss

Leakage inductance energy
$$P_{LEAK} = \frac{L_{LEAK} \cdot I_{SW-PK}^2}{2} \cdot F_{SW}$$

- Large percentage of this power dissipated in external clamp circuit or RC snubber
- Magnetizing energy also dissipated depends on clamp level and leakage inductance

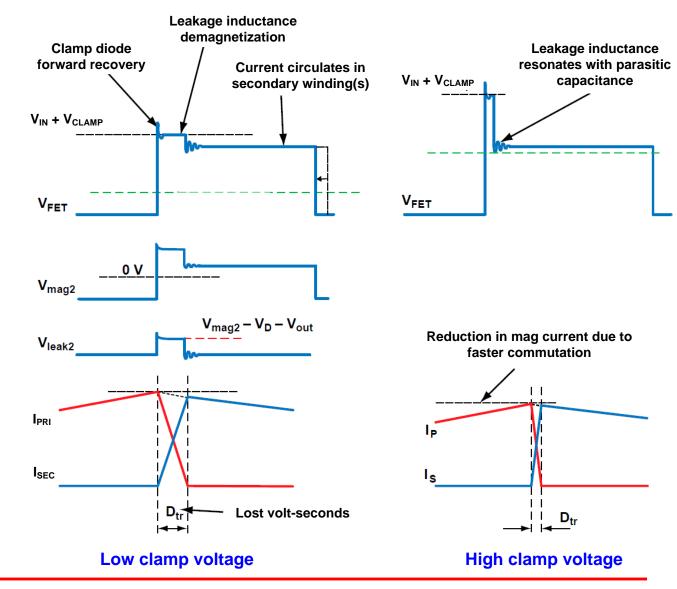


Flyback transformer – impact of leakage inductance



Leakage inductance affects:

- Conversion efficiency
- Voltage spikes during commutation
 - clamp circuits and snubbers
- Current slew rate & loss of volt-seconds
- H-field radiated EMI
- Cross regulation in multi-output designs



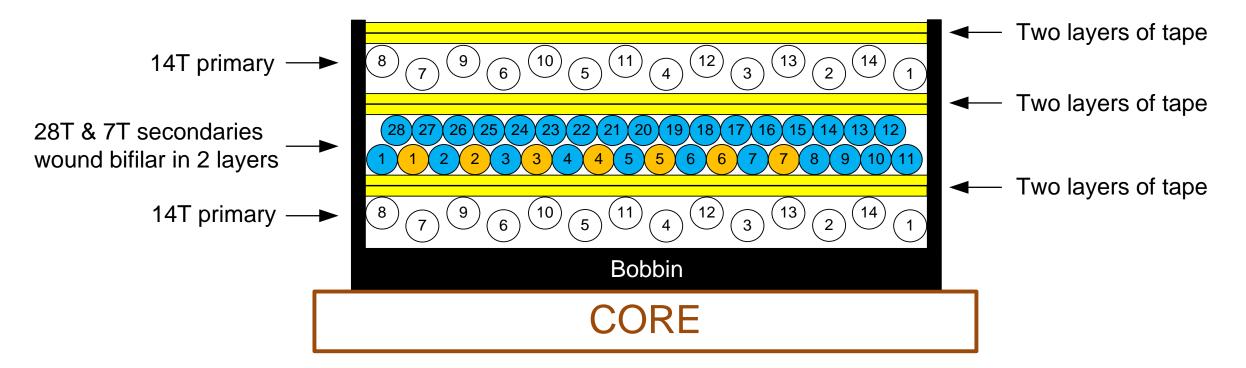


Flyback transformer design – impact on efficiency / x-reg

- 1. Guidelines to optimize efficiency
 - Choose the transformer turns ratio for best efficiency and duty cycle range
 - Minimize leakage inductance from primary to main (high-current) secondary
 - Interleave primary around secondary (or vice versa if $N_P < N_S$)
 - Reduces voltage spikes and power dissipation
 - Locate highest power secondary closest to primary (multi-output designs)
 - Minimize transformer high-frequency conduction loss
 - Use bifilar or multifilar wires when necessary to reduce AC resistance
 - Interleave primary and secondary windings
 - Select core shape for minimum number of layers (wide bobbin width)
- 2. Guidelines to optimize cross regulation
 - Minimize leakage inductance between secondary windings as it impacts cross regulation and secondary current wave shapes
 - Wind two highest power secondaries bifilar for best coupling
 - Consider DC or AC stacking for same polarity outputs that share common GND



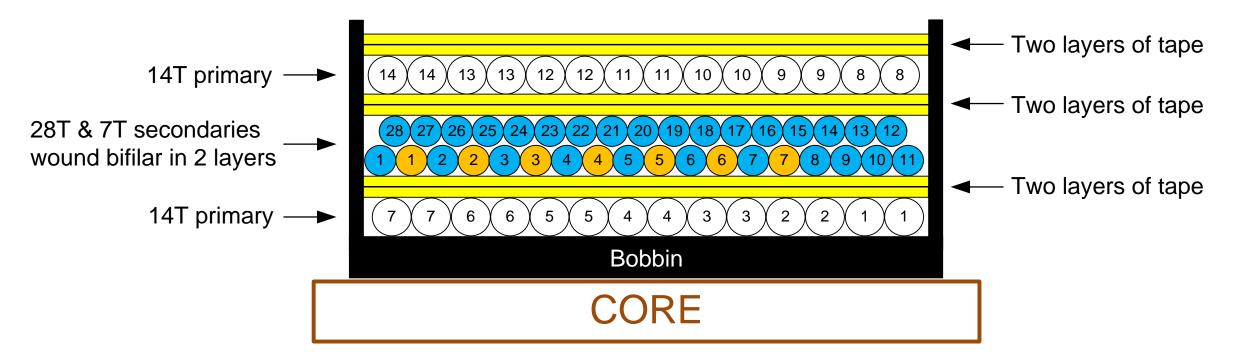
Dual-output transformer construction #1 14 : 28 : 7



Primary winding 50/50 parallel split

Parallel primary windings is a more convenient construction, but the **high dv/dt (noisy) SW node voltage** appears both on the inner and outer layers

Dual-output transformer construction #2 14 : 28 : 7



Primary winding 50/50 series split

Wind first half of primary on inside layer nearest the bobbin and the other half on the outside

- \rightarrow Noisy node (SW) shielded on inside & quiet node (VIN) connects to outside layer
- \rightarrow Place windings with similar dv/dt adjacent to each other to reduce interwinding capacitance
- \rightarrow Better common-mode EMI performance

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